



A T S H S / S /

D	2017-5				
E	2021-1-27	4/7	0.5-0.8	e0.5-0.7 5 7	



Rev.E Jan.-2021

2.0A

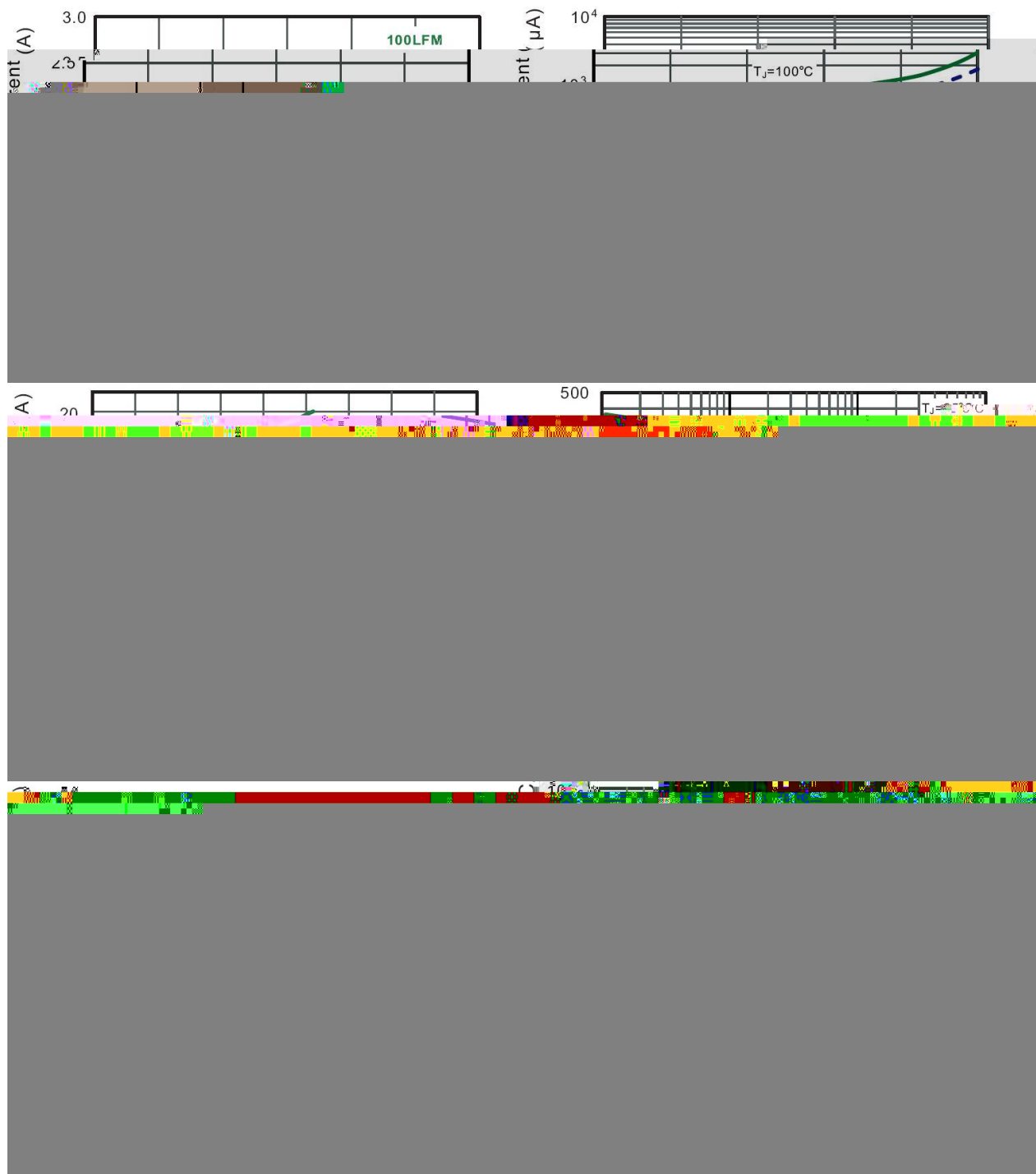


Parameter	Symbol	Rating					Unit
		MB24F	MB26F	MB28F	MB210F	MB220F	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	40	60	80	100	200	V
Maximum RMS Voltage	V _{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V _{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	2.0					A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	50		40			A
Typical Junction Capacitance ¹⁾	C _j	220	80				pF
Typical Thermal Resistance ²⁾	R _{θJA}	75					/W
Operating Junction Temperature Range	T _j	-55~+125					
Storage Temperature Range	T _{stg}	-55~+150					

Note:

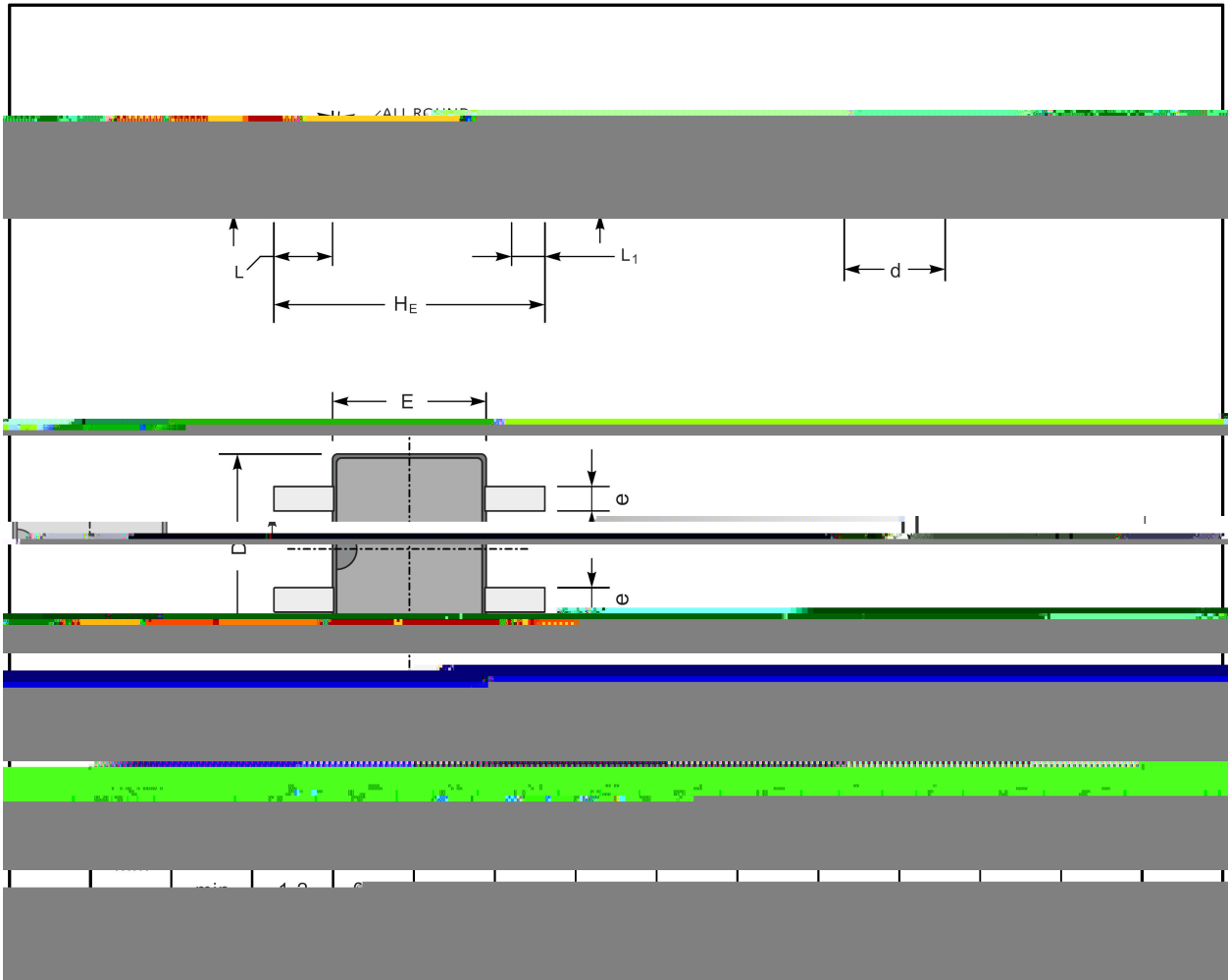
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with $4 \times (5 \times 5 \text{mm}^2)$ copper pad.

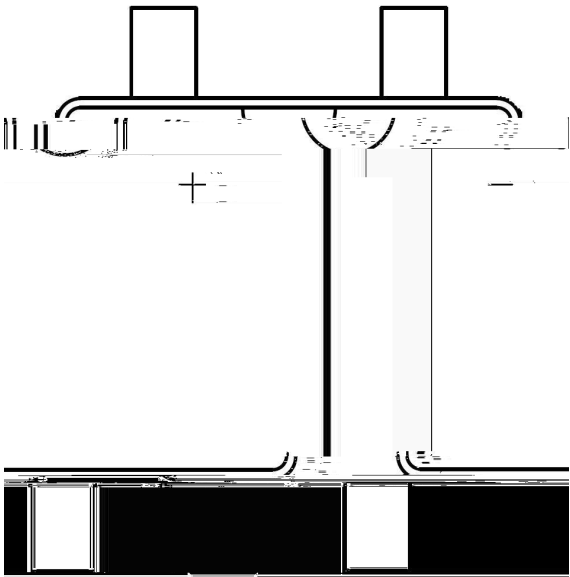
Parameter	Symbol	Test Conditions	数值 Rating					Unit
			MB24F	MB26F	MB28F	MB210F	MB220F	
Max Instantaneous Forward Voltage	V_F	$I_F=2.0\text{A}$	0.55	0.70	0.85			V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25^\circ\text{C}$	0.5			0.3		mA
		$T_a=100^\circ\text{C}$	10			5.0		mA





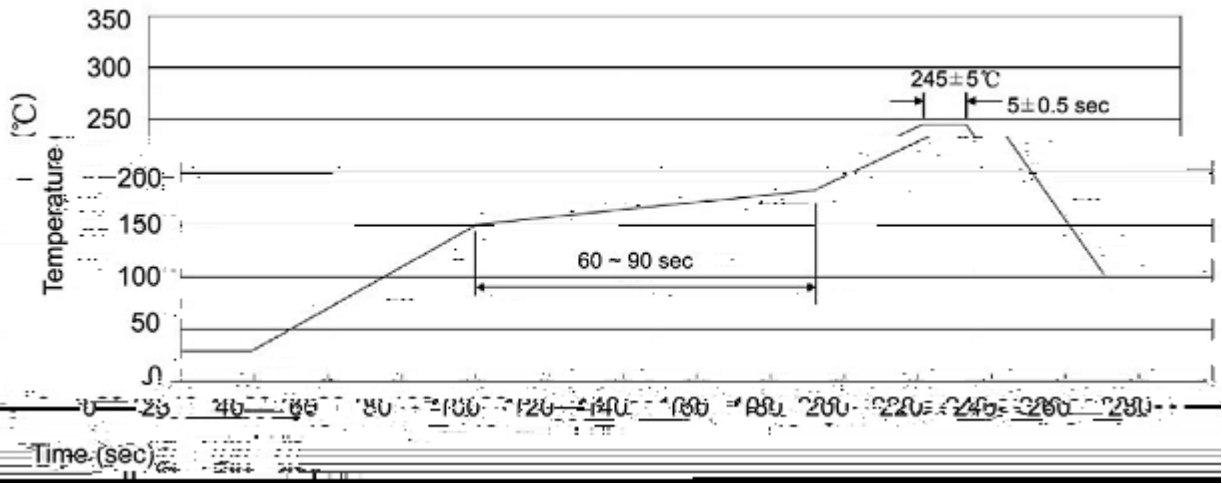
MBF







Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

245±5

5±0.5sec;
- 3

2 10 /sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:245±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

260±5

10±1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱